

# TLP2662, TLP2662F

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## 1. Applications

- Factory Automation (FA)
- High-Speed Digital Interfacing for Instrumentation and Control Devices
- Measuring Instruments

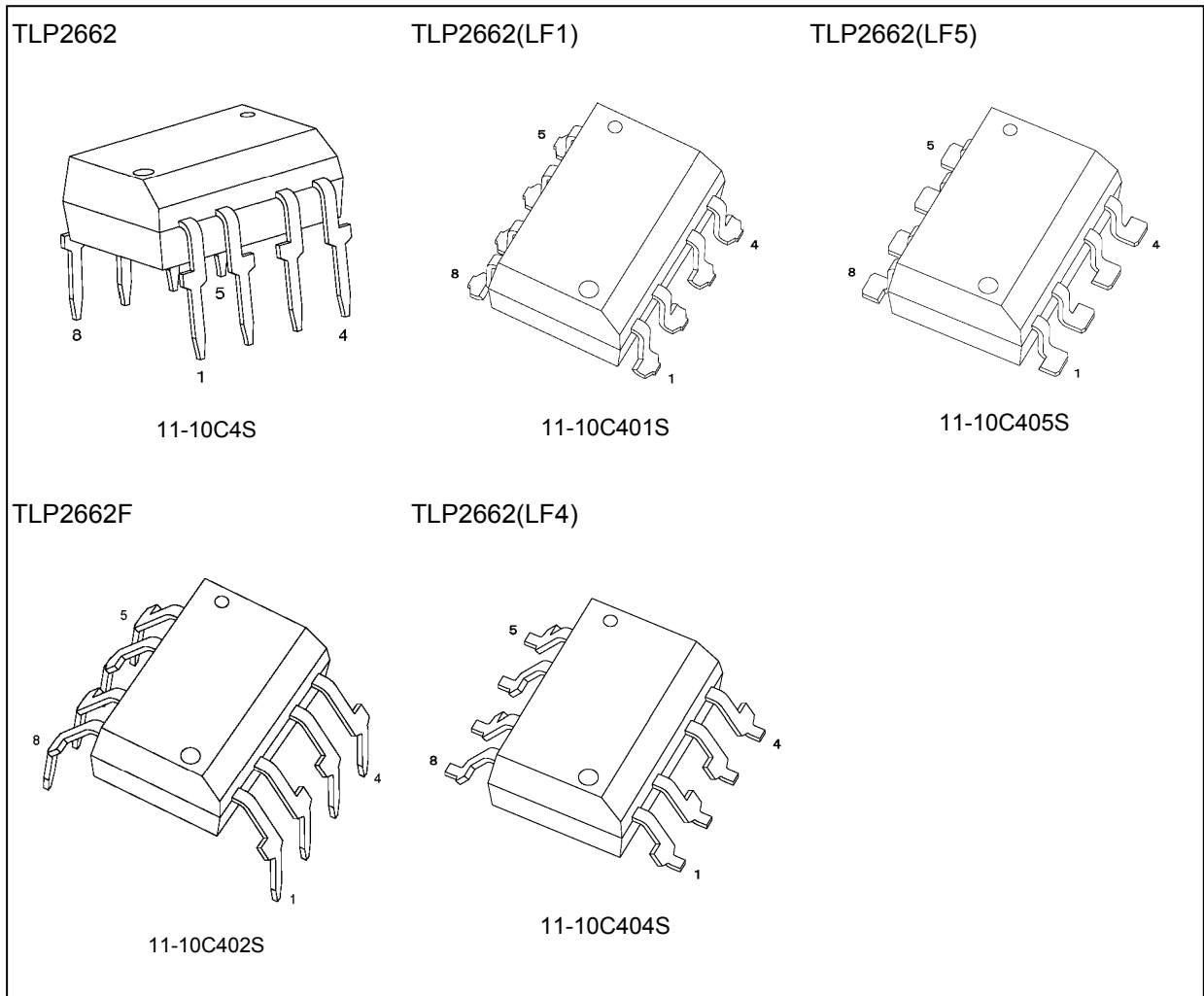
## 2. General

The TLP2662/TLP2662F consists of high-intensity GaAs infrared light-emitting diodes (LEDs) optically coupled to a high-gain, high-speed photoreceptor chip. The TLP2662/TLP2662F guarantees operation at up to 125°C and on supplies from 2.7 V to 5.5 V. It is offered in the DIP8 package. With two LED-photoreceptor pairs, the TLP2662/TLP2662F helps save board space. An internal noise shield provides superior common-mode rejection for improved noise immunity.

## 3. Features

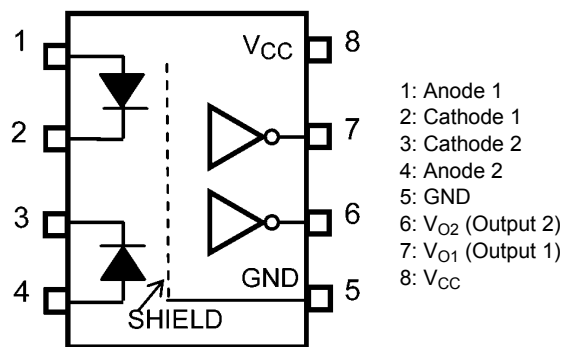
- (1) Inverter logic type (open collector output)
- (2) Package: DIP8
- (3) Operating temperature: -40 to 125°C
- (4) Supply voltage: 2.7 to 5.5 V
- (5) Data transfer rate: 10 MBd (typ.) (NRZ)
- (6) Threshold input current: 5.0 mA (max)
- (7) Supply current: 8 mA (max)
- (8) Common-mode transient immunity:  $\pm 20$  kV/ $\mu$ s (min)
- (9) Isolation voltage: 5000 Vrms (min)
- (10) Safety standards
  - UL-under application: UL1577 File No.E67349
  - cUL-under application: CSA Component Acceptance Service No.5A, File No.E67349
  - VDE-under application: Option (D4) EN60747-5-5

**4. Packaging (Note)**

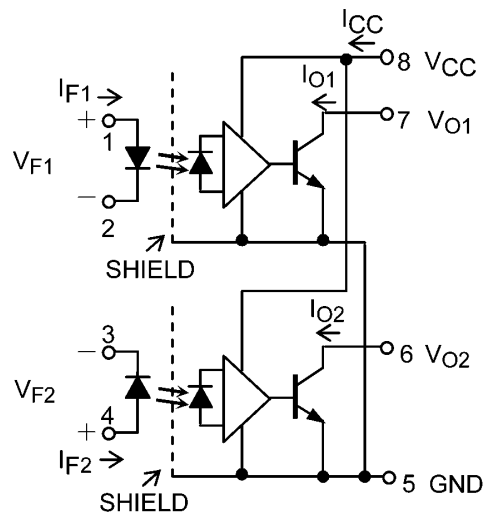


Note: Lead-formed product: (LF1), (LF4), (LF5)

**5. Pin Assignment**



**6. Internal Circuit**



**7. Principle of Operation**

**7.1. Truth Table**

Input	LED	Output
H	ON	L
L	OFF	H

**7.2. Mechanical Parameters**

Characteristics	7.62-mm pitch TLP2662	10.16-mm pitch TLP2662F	Unit
Creepage distances	7.0 (min)	8.0 (min)	mm
Clearance distances	7.0 (min)	8.0 (min)	mm
Internal isolation thickness	0.4 (min)	0.4 (min)	mm

**8. Absolute Maximum Ratings (Note) (Unless otherwise specified,  $T_a = 25^\circ\text{C}$ )**

	Characteristics	Test Condition	Symbol	Note	Rating	Unit
LED	Input forward current		$I_F$	(Note 1)	20	mA
	Input forward current derating	$(T_a \geq 116^\circ\text{C})$	$\Delta I_F/\Delta T_a$	(Note 1)	-0.6	mA/ $^\circ\text{C}$
	Input forward current (pulsed)		$I_{FP}$	(Note 1), (Note 2)	40	mA
	Input forward current derating (pulsed)	$(T_a \geq 116^\circ\text{C})$	$\Delta I_{FP}/\Delta T_a$	(Note 1)	-1.17	mA/ $^\circ\text{C}$
	Peak transient input forward current		$I_{FPT}$	(Note 1), (Note 3)	1	A
	Peak transient input forward current derating	$(T_a \geq 116^\circ\text{C})$	$\Delta I_{FPT}/\Delta T_a$	(Note 1)	-29.4	mA/ $^\circ\text{C}$
	Input power dissipation		$P_D$	(Note 1)	40	mW
	Input power dissipation derating	$(T_a \geq 116^\circ\text{C})$	$\Delta P_D/\Delta T_a$	(Note 1)	-1.17	mW/ $^\circ\text{C}$
	Input reverse voltage		$V_R$	(Note 1)	5	V
Detector	Output current		$I_O$	(Note 1)	25	mA
	Output voltage		$V_O$	(Note 1)	6	V
	Supply voltage		$V_{CC}$		6	V
	Output power dissipation		$P_O$	(Note 1)	85	mW
	Output power dissipation derating	$(T_a \geq 110^\circ\text{C})$	$\Delta P_O/\Delta T_a$	(Note 1)	-2.1	mW/ $^\circ\text{C}$
Common	Operating temperature		$T_{opr}$		-40 to 125	$^\circ\text{C}$
	Storage temperature		$T_{stg}$		-55 to 150	$^\circ\text{C}$
	Lead soldering temperature	(10 s)	$T_{sol}$		260	$^\circ\text{C}$
	Isolation voltage	AC, 1 min., R.H. $\leq$ 60%	$BV_S$	(Note 4)	5000	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Each channel

Note 2: Pulse width (PW)  $\leq$  1 ms, duty = 50%

Note 3: Pulse width (PW)  $\leq$  1  $\mu\text{s}$ , duty = 300 pps

Note 4: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

**9. Recommended Operating Conditions (Note)**

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
Input on-state current	$I_{F(ON)}$	(Note 1), (Note 2)	6	—	15	mA
Input off-state voltage	$V_{F(OFF)}$	(Note 1)	0	—	0.8	V
Supply voltage	$V_{CC}$	(Note 3)	2.7	3.3/5.0	5.5	V
Operating temperature	$T_{opr}$		-40	—	125	$^\circ\text{C}$

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

Note: A ceramic capacitor (0.1  $\mu\text{F}$ ) should be connected between pin 8 and pin 5 to stabilize the operation of a high-gain linear amplifier. Otherwise, this photocoupler may not switch properly. The bypass capacitor should be placed within 1 cm of each pin.

Note 1: Each channel

Note 2: The rise and fall times of the input on-current should be less than 0.5  $\mu\text{s}$ .

Note 3: Denotes the operating range, not the recommended operating condition.

**10. Electrical Characteristics (Note)**  
 (Unless otherwise specified,  $T_a = -40$  to  $125^\circ\text{C}$ ,  $V_{CC} = 2.7$  to  $5.5$  V)

Characteristics	Symbol	Note	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Input forward voltage	$V_F$	(Note 1)		$I_F = 10$ mA, $T_a = 25^\circ\text{C}$	1.45	1.55	1.7	V
Input forward voltage temperature coefficient	$\Delta V_F / \Delta T_a$	(Note 1)		$I_F = 10$ mA	—	-2.0	—	mV/ $^\circ\text{C}$
Input reverse current	$I_R$	(Note 1)		$V_R = 5$ V, $T_a = 25^\circ\text{C}$	—	—	10	$\mu\text{A}$
Input capacitance	$C_t$	(Note 1)		$V = 0$ V, $f = 1$ MHz, $T_a = 25^\circ\text{C}$	—	60	—	pF
High-level output current	$I_{OH}$	(Note 1)	Fig. 13.1.1	$V_F = 0.8$ V, $V_O = 5.5$ V, $V_{CC} = 5.5$ V	—	—	50	$\mu\text{A}$
			Fig. 13.1.1	$V_F = 0.8$ V, $V_O = 5.5$ V, $V_{CC} = 5.5$ V, $T_a = 25^\circ\text{C}$	—	—	10	$\mu\text{A}$
Low-level output voltage	$V_{OL}$	(Note 1)	Fig. 13.1.2	$I_F = 10$ mA, $I_O = 13$ mA (Sinking)	—	0.2	0.6	V
Low-level supply current	$I_{CCL}$		Fig. 13.1.4	$I_{F1} = I_{F2} = 10$ mA	—	3.8	8	mA
High-level supply current	$I_{CCH}$		Fig. 13.1.3	$I_{F1} = I_{F2} = 0$ mA	—	3.4	8	mA
Threshold input current (H/L)	$I_{FHL}$	(Note 1)		$I_O = 13$ mA (Sinking), $V_O < 0.6$ V, $T_a = 25^\circ\text{C}$	—	1.3	2.8	mA
				$I_O = 13$ mA (Sinking), $V_O < 0.6$ V	—	—	5.0	mA

Note: All typical values are at  $T_a = 25^\circ\text{C}$ .

Note 1: Each channel

**11. Isolation Characteristics (Unless otherwise specified,  $T_a = 25^\circ\text{C}$ )**

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	$C_S$	(Note 1)	$V_S = 0$ V, $f = 1$ MHz	—	1.0	—	pF
Isolation resistance	$R_S$	(Note 1)	$V_S = 500$ V, R.H. $\leq 60\%$	$1 \times 10^{12}$	$10^{14}$	—	$\Omega$
Isolation voltage	$BV_S$	(Note 1)	AC, 1 min	5000	—	—	Vrms
			AC, 1 s in oil	—	10000	—	Vrms
			DC, 1min in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1, 2, 3 and 4 are shorted together, and pins 5, 6, 7 and 8 are shorted together.

**12. Switching Characteristics (Note)**  
**(Unless otherwise specified,  $T_a = -40$  to  $125^\circ\text{C}$ ,  $V_{CC} = 2.7$  to  $5.5$  V (Each channel))**

Characteristics	Symbol	Note	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Propagation delay time (H/L)	$t_{pHL}$	(Note 1)	Fig. 13.1.5	$I_F = 0 \rightarrow 7.5$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	—	27	75	ns
Propagation delay time (L/H)	$t_{pLH}$	(Note 1)	Fig. 13.1.5	$I_F = 7.5 \rightarrow 0$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	—	25	75	ns
Pulse width distortion	$ \mathit{t}_{pHL} - \mathit{t}_{pLH} $	(Note 1)	Fig. 13.1.5	$I_F = 0 \leftrightarrow 7.5$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	—	—	35	ns
Propagation delay skew (device to device)	$t_{psk}$	(Note 1), (Note 2)	Fig. 13.1.5	$I_F = 0 \leftrightarrow 7.5$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	-40	—	40	ns
Fall time	$t_f$	(Note 1)	Fig. 13.1.5	$I_F = 0 \rightarrow 7.5$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	—	3	—	ns
Rise time	$t_r$	(Note 1)	Fig. 13.1.5	$I_F = 7.5 \rightarrow 0$ mA, $R_L = 350 \Omega$ , $C_L = 15$ pF	—	12	—	ns
Common-mode transient immunity at output high	$CM_H$		Fig. 13.1.6	$V_{CM} = 1000$ V <sub>p-p</sub> , $I_F = 0$ mA, $V_{CC} = 3.3$ V/5 V, $T_a = 25^\circ\text{C}$	$\pm 20$	$\pm 25$	—	kV/ $\mu$ s
Common-mode transient immunity at output low	$CM_L$		Fig. 13.1.6	$V_{CM} = 1000$ V <sub>p-p</sub> , $I_F = 10$ mA, $V_{CC} = 3.3$ V/5 V, $T_a = 25^\circ\text{C}$	$\pm 20$	$\pm 25$	—	kV/ $\mu$ s

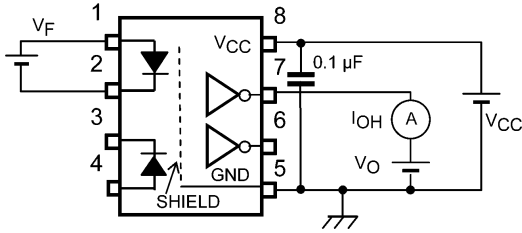
Note: All typical values are at  $T_a = 25^\circ\text{C}$ .

Note 1:  $f = 5$  MHz, duty = 50%, input current  $t_r = t_f = 5$  ns,  $C_L$  is approximately 15 pF which includes probe and stray wiring capacitance.

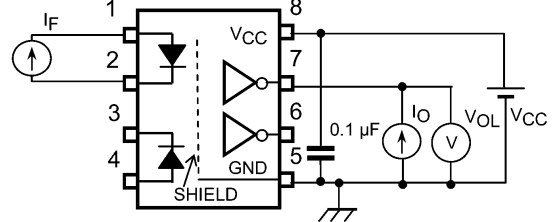
Note 2: The propagation delay skew,  $t_{psk}$ , is equal to the magnitude of the worst-case difference in  $t_{pHL}$  and/or  $t_{pLH}$  that will be seen between units at the same given conditions (supply voltage, input current, temperature, etc).

**13. Test Circuits and Characteristics Curves**

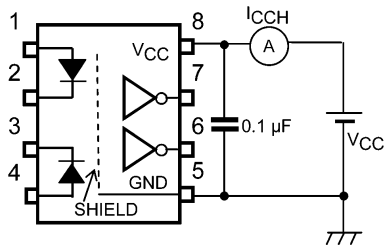
**13.1. Test Circuits**



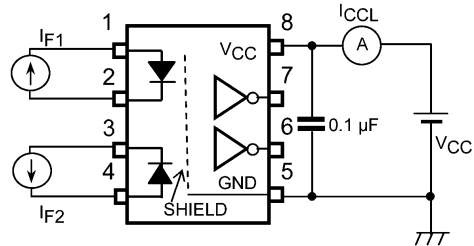
**Fig. 13.1.1 IOH Test Circuit**



**Fig. 13.1.2 VOL Test Circuit**

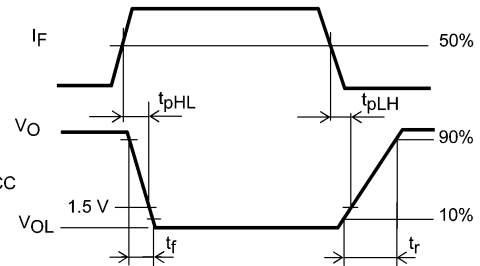
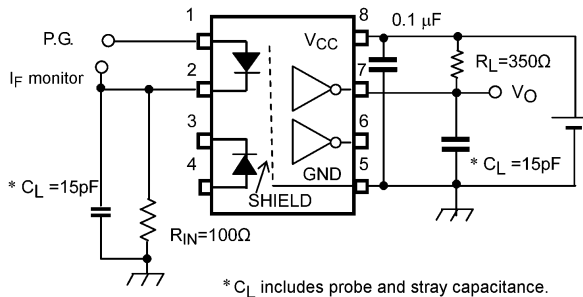


**Fig. 13.1.3 ICCH Test Circuit**



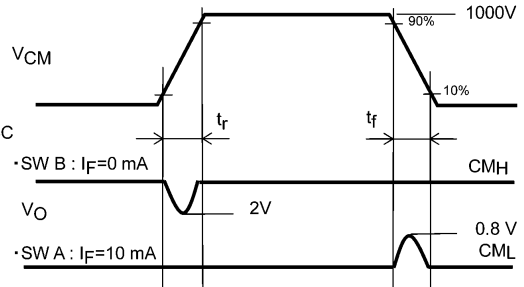
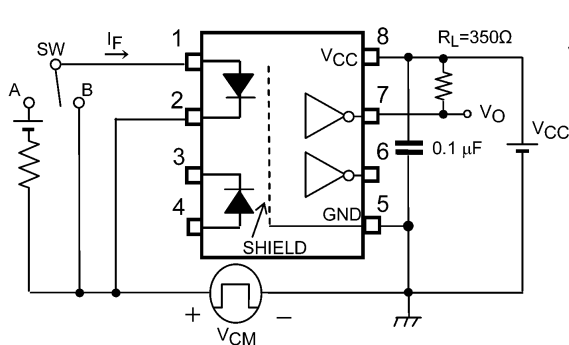
**Fig. 13.1.4 ICCL Test Circuit**

$I_F = 7.5\text{mA (P.G.)}$   
 $(f = 5\text{MHz, duty} = 50\%, t_r = t_f = 5\text{ns or less})$



\*  $C_L$  includes probe and stray capacitance.  
 P.G.: Pulse Generator

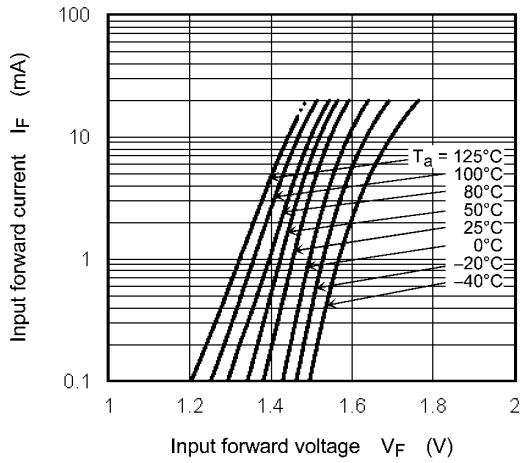
**Fig. 13.1.5 Switching Time Test Circuit and Waveform**



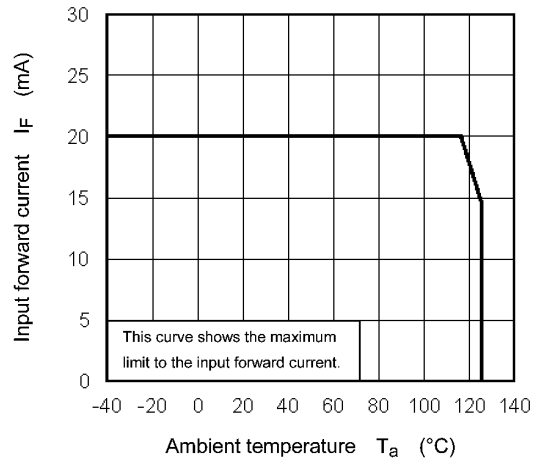
$$CM_H = \frac{800(V)}{t_r (\mu s)} \quad CM_L = - \frac{800(V)}{t_f (\mu s)}$$

**Fig. 13.1.6 Common-Mode Transient Immunity and Waveform**

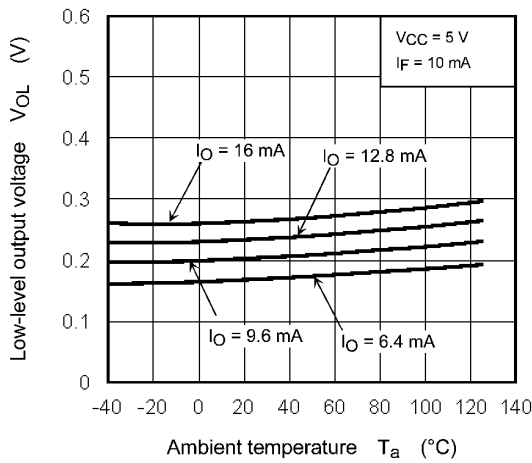
**13.2. Characteristics Curves (Note)**



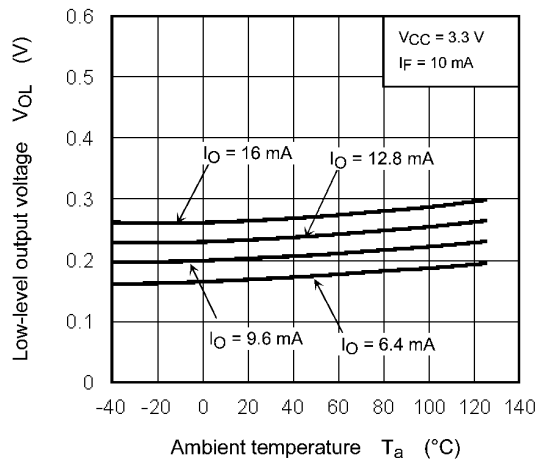
**Fig. 13.2.1  $I_F - V_F$**



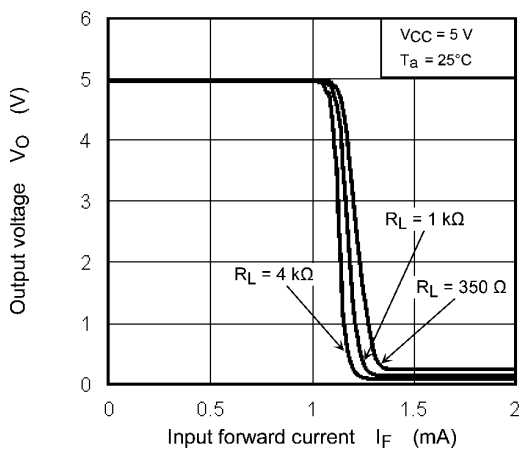
**Fig. 13.2.2  $I_F - T_a$**



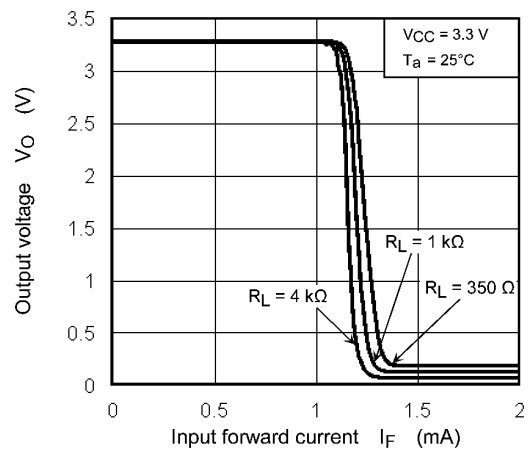
**Fig. 13.2.3  $V_{OL} - T_a$**



**Fig. 13.2.4  $V_{OL} - T_a$**

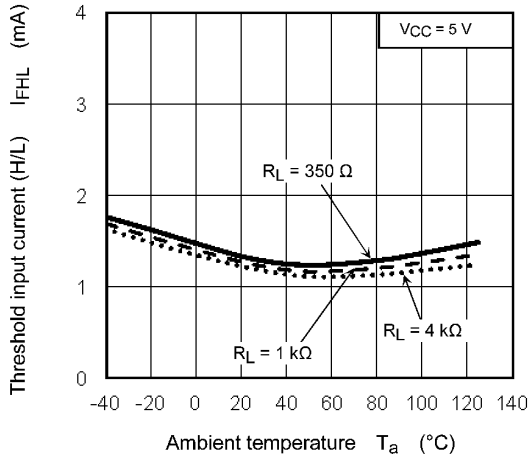


**Fig. 13.2.5  $V_O - I_F$**

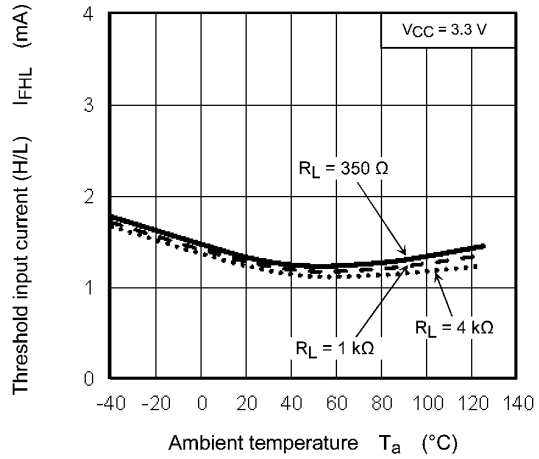


**Fig. 13.2.6  $V_O - I_F$**

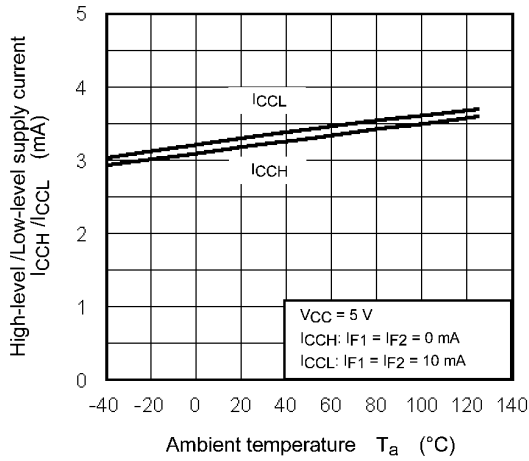




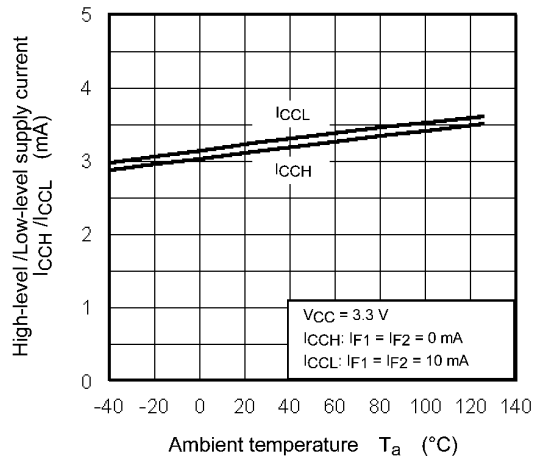
**Fig. 13.2.7**  $I_{FHL} - T_a$



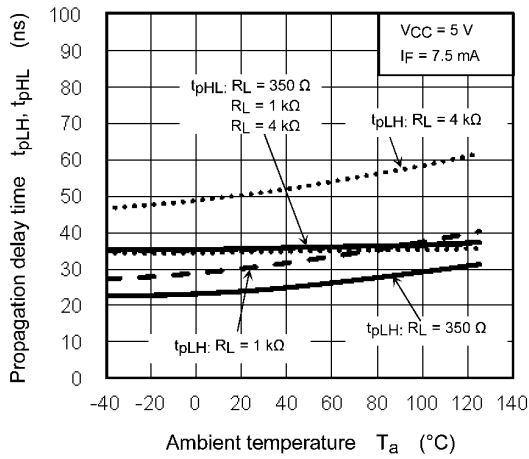
**Fig. 13.2.8**  $I_{FHL} - T_a$



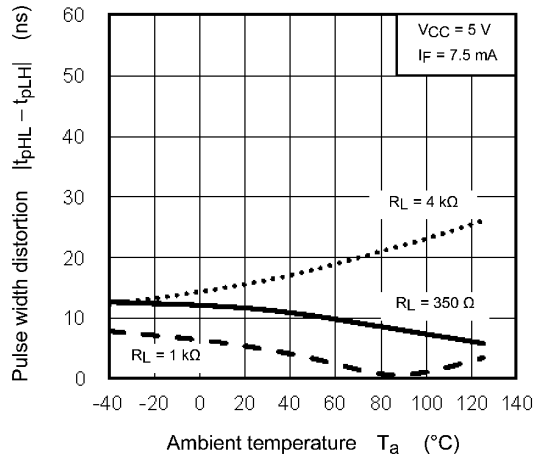
**Fig. 13.2.9**  $I_{CCH} / I_{CCL} - T_a$



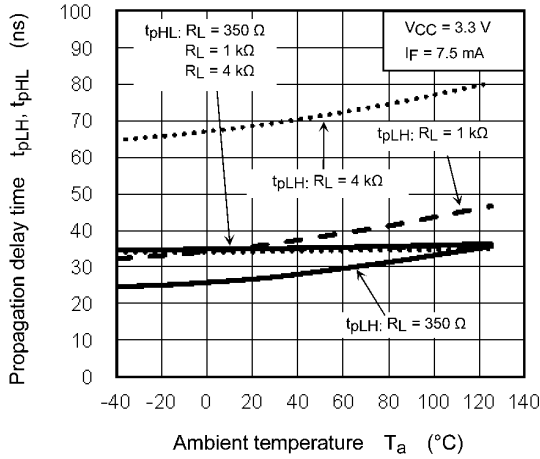
**Fig. 13.2.10**  $I_{CCH} / I_{CCL} - T_a$



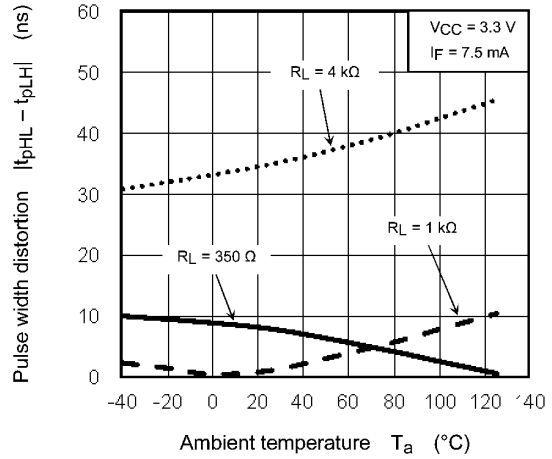
**Fig. 13.2.11**  $t_{pLH} / t_{pHL} - T_a$



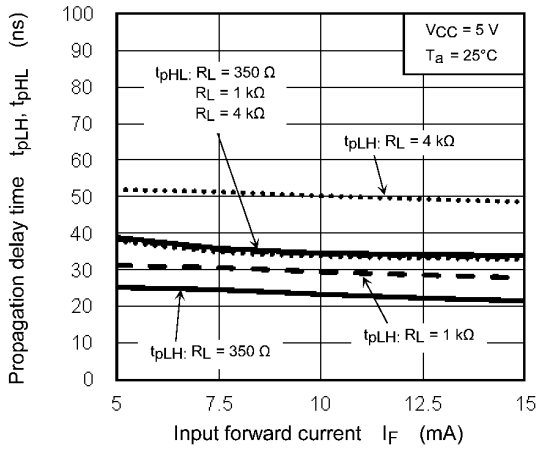
**Fig. 13.2.12**  $|t_{pHL} - t_{pLH}| - T_a$



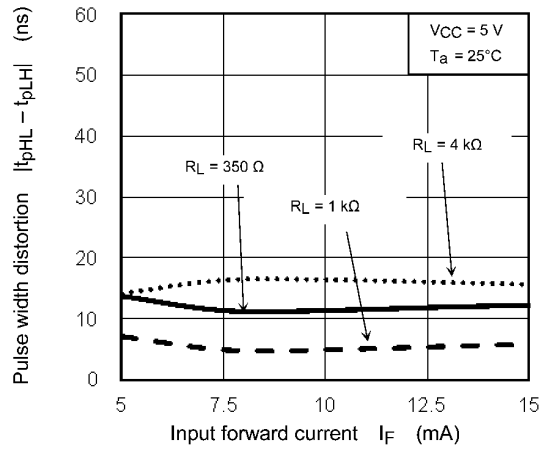
**Fig. 13.2.13**  $t_{pLH} / t_{pHL} - T_a$



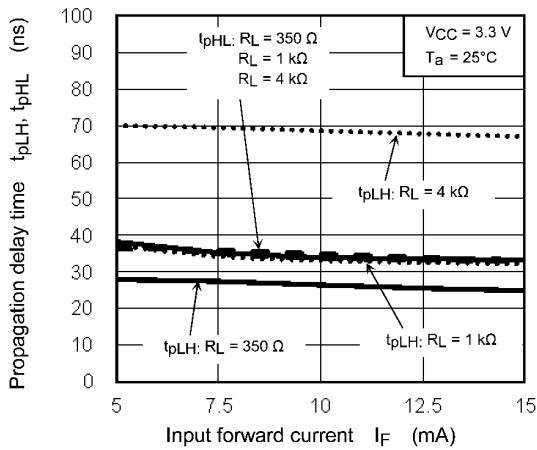
**Fig. 13.2.14**  $|t_{pHL} - t_{pLH}| - T_a$



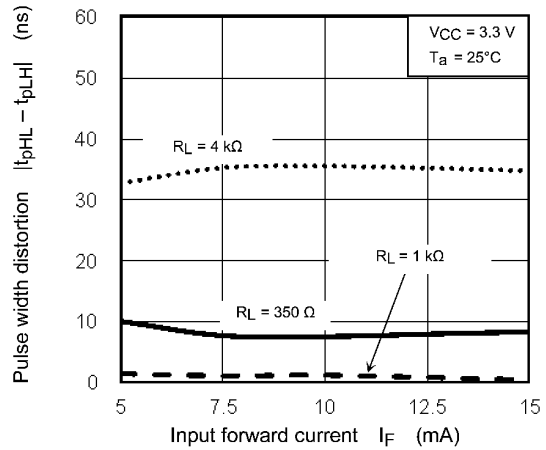
**Fig. 13.2.15**  $t_{pLH} / t_{pHL} - I_F$



**Fig. 13.2.16**  $|t_{pHL} - t_{pLH}| - I_F$



**Fig. 13.2.17**  $t_{pLH} / t_{pHL} - I_F$



**Fig. 13.2.18**  $|t_{pHL} - t_{pLH}| - I_F$

NOTE: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

**14. Soldering and Storage**

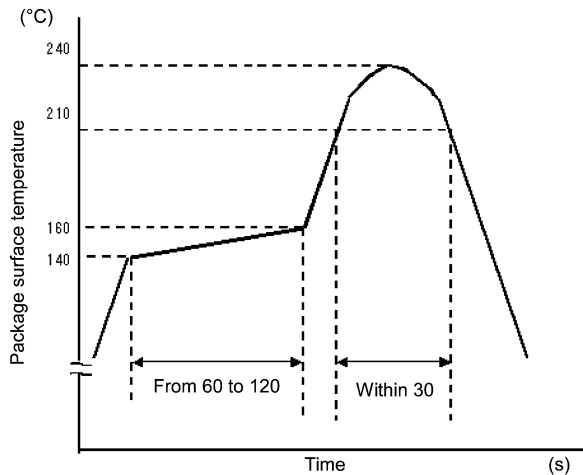
**14.1. Precautions for Soldering**

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

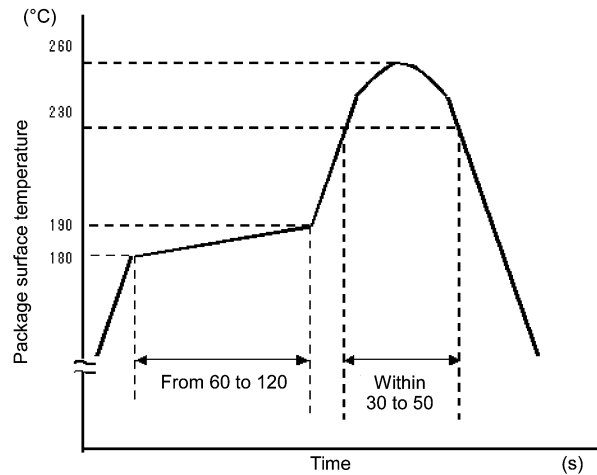
- When using soldering reflow (See Fig. 14.1.1 and 14.1.2)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.



**Fig. 14.1.1 An Example of a Temperature Profile When Sn-Pb Eutectic Solder Is Used**



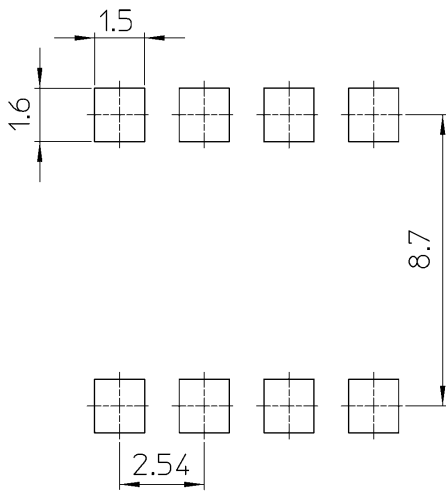
**Fig. 14.1.2 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used**

- When using soldering flow (Applicable to both eutectic solder and Lead(Pb)-Free solder)  
Apply preheating of 150°C for 60 to 120 seconds.  
Mounting condition of 260°C within 10 seconds is recommended.  
Flow soldering must be performed once.
- When using soldering Iron (Applicable to both eutectic solder and Lead(Pb)-Free solder)  
Complete soldering within 10 seconds for lead temperature not exceeding 260°C or within 3 seconds not exceeding 350°C Heating by soldering iron must be done only once per lead.

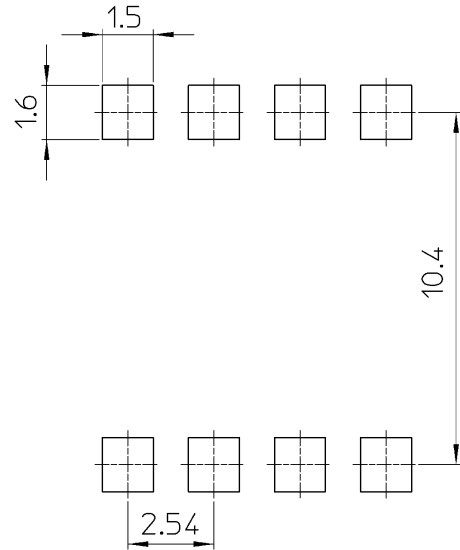
**14.2. Precautions for General Storage**

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5°C to 35°C and 45% to 75%, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

**15. Land Pattern Dimensions (for reference only)**

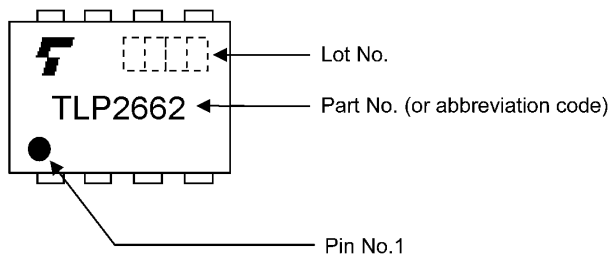


**Fig. 15.1 (LF1), (LF5) Type (unit: mm)**

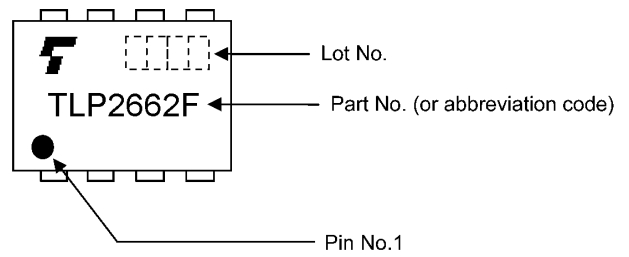


**Fig. 15.2 (LF4) Type (unit: mm)**

**16. Marking**



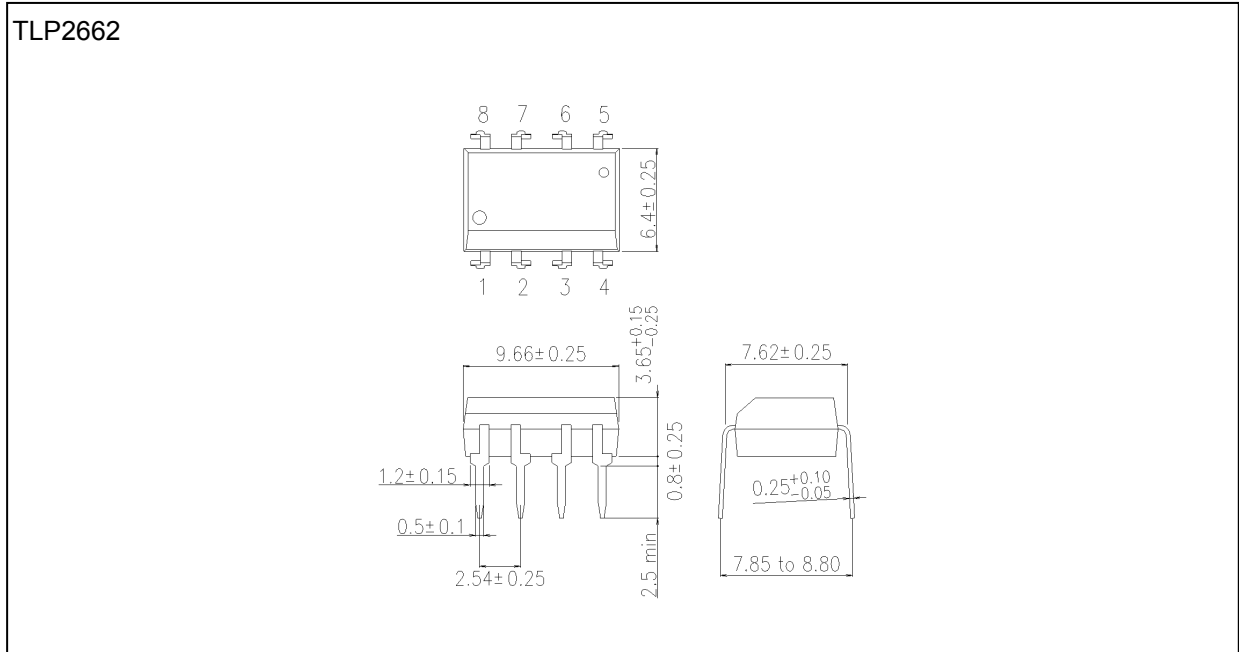
**Fig. 16.1 TLP2662**



**Fig. 16.2 TLP2662F**

**Package Dimensions**

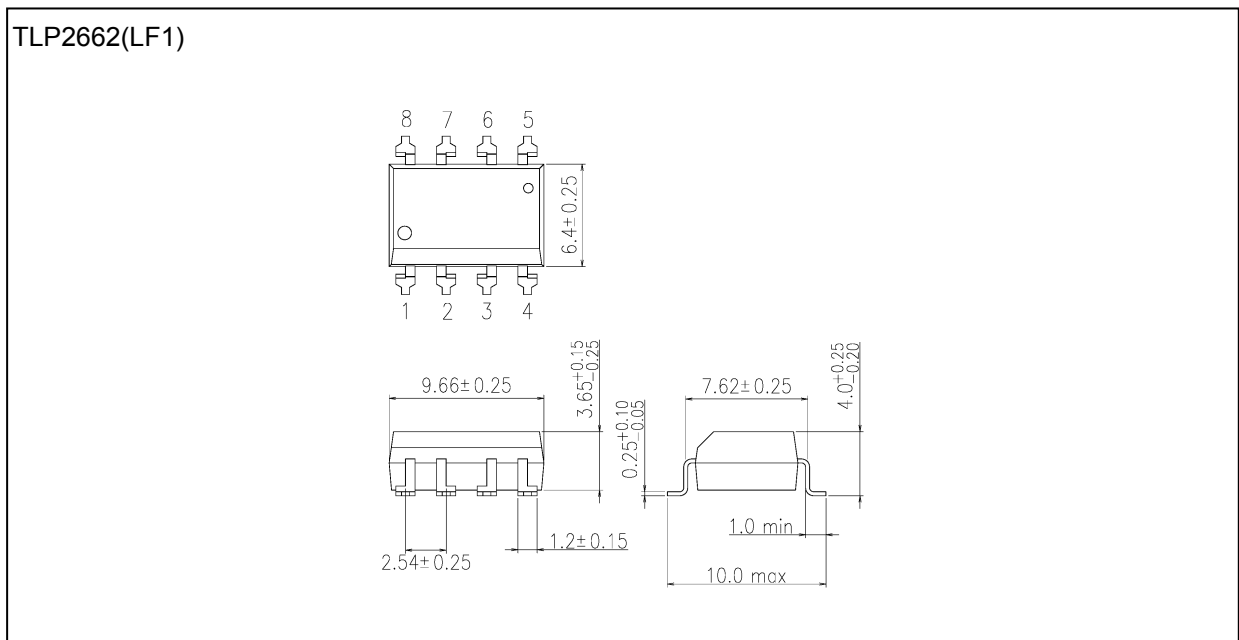
Unit: mm



Weight: 0.54 g (typ.)

Package Name(s)
TOSHIBA: 11-10C4S

Unit: mm

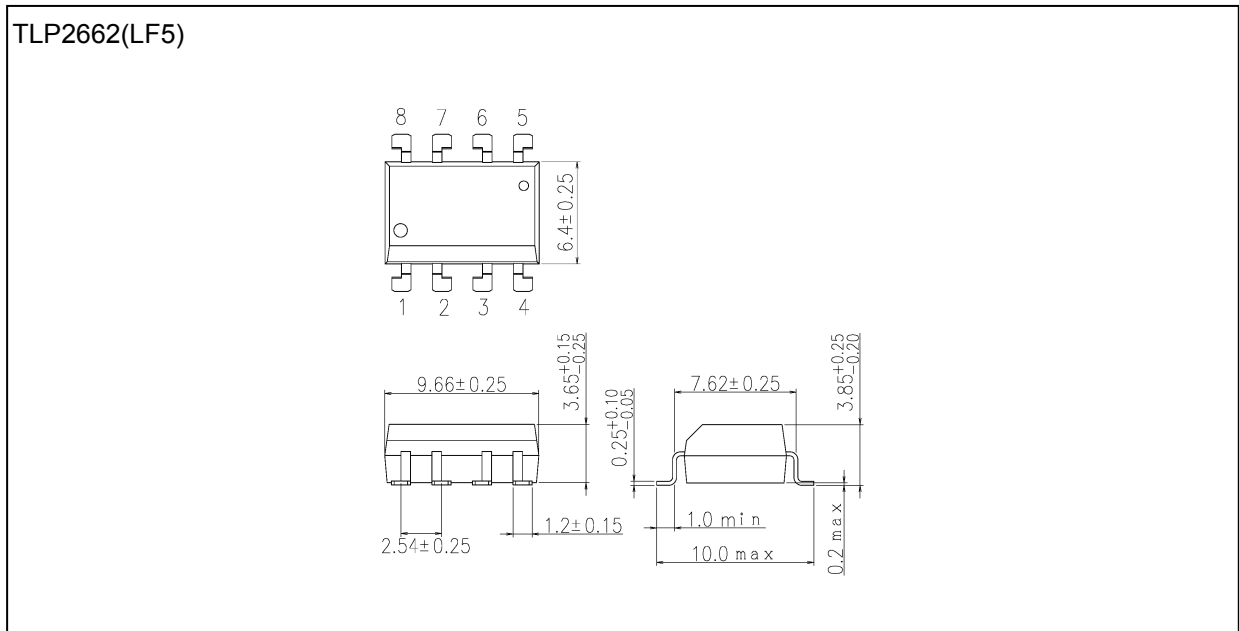


Weight: 0.53 g (typ.)

Package Name(s)
TOSHIBA: 11-10C401S

**Package Dimensions**

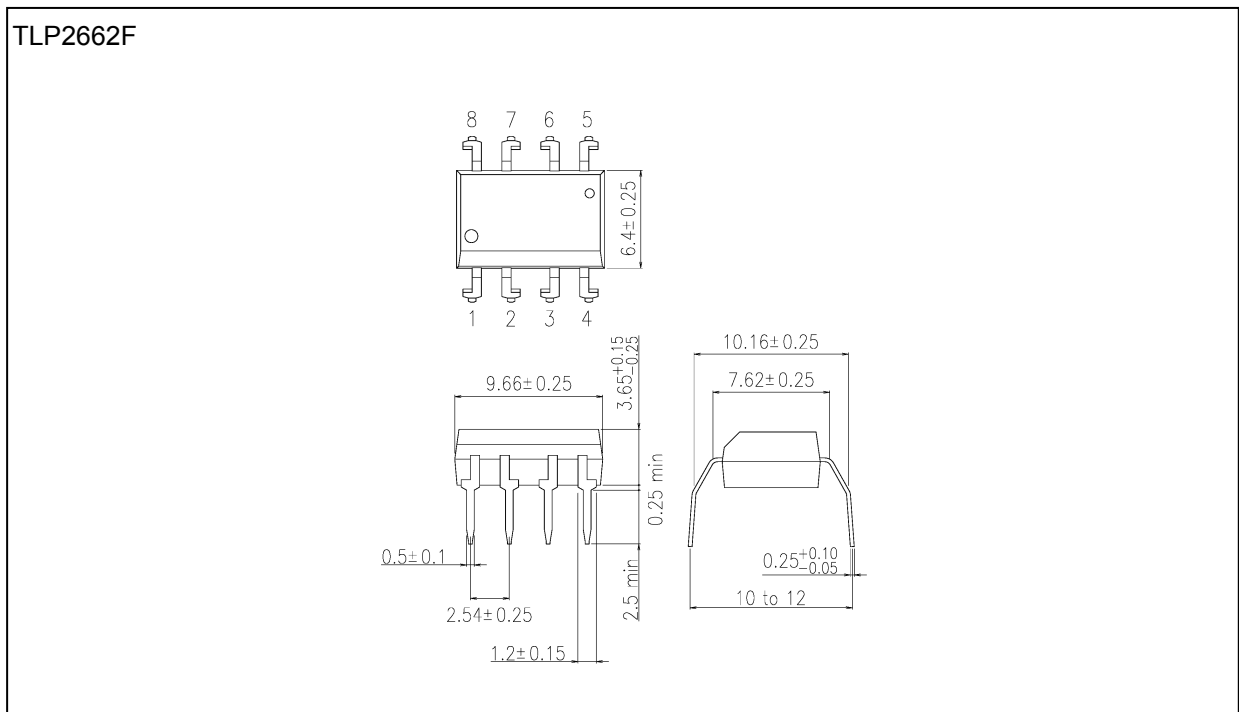
Unit: mm



Weight: 0.53 g (typ.)

Package Name(s)
TOSHIBA: 11-10C405S

Unit: mm

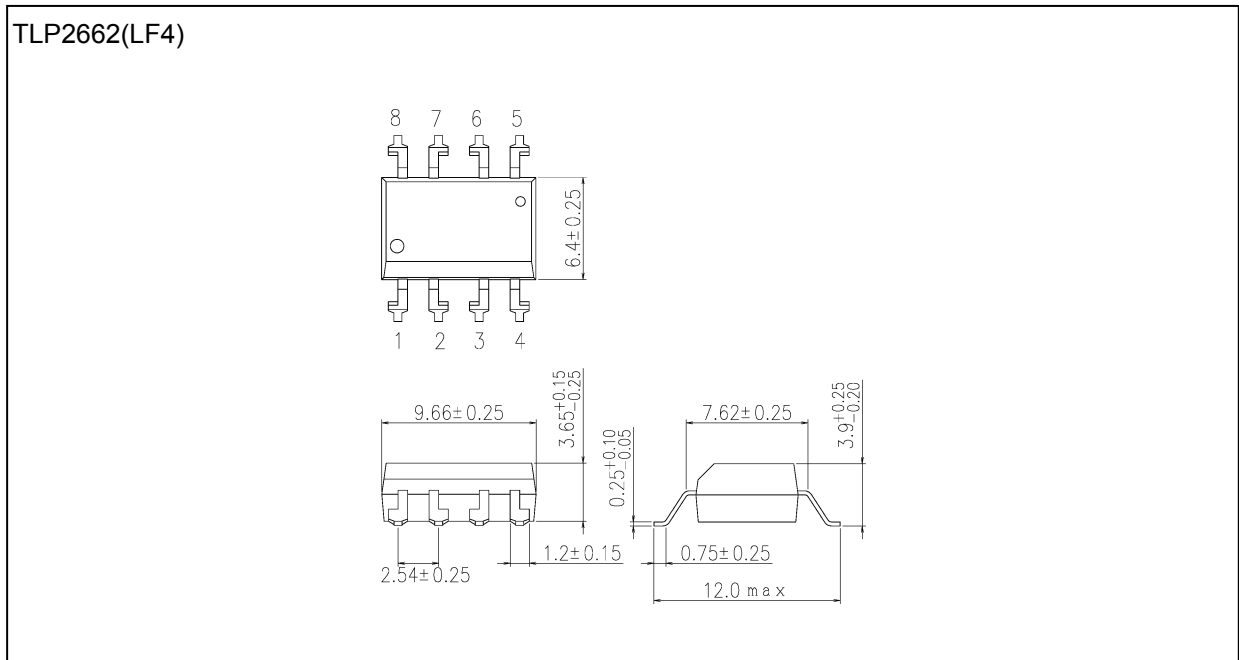


Weight: 0.54 g (typ.)

Package Name(s)
TOSHIBA: 11-10C402S

**Package Dimensions**

Unit: mm



Weight: 0.53 g (typ.)

Package Name(s)
TOSHIBA: 11-10C404S

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